


DIFFERENTIAL-TO-0.7V DIFFERENTIAL PCI EXPRESS™ JITTER ATTENUATOR

ICS871004I-04

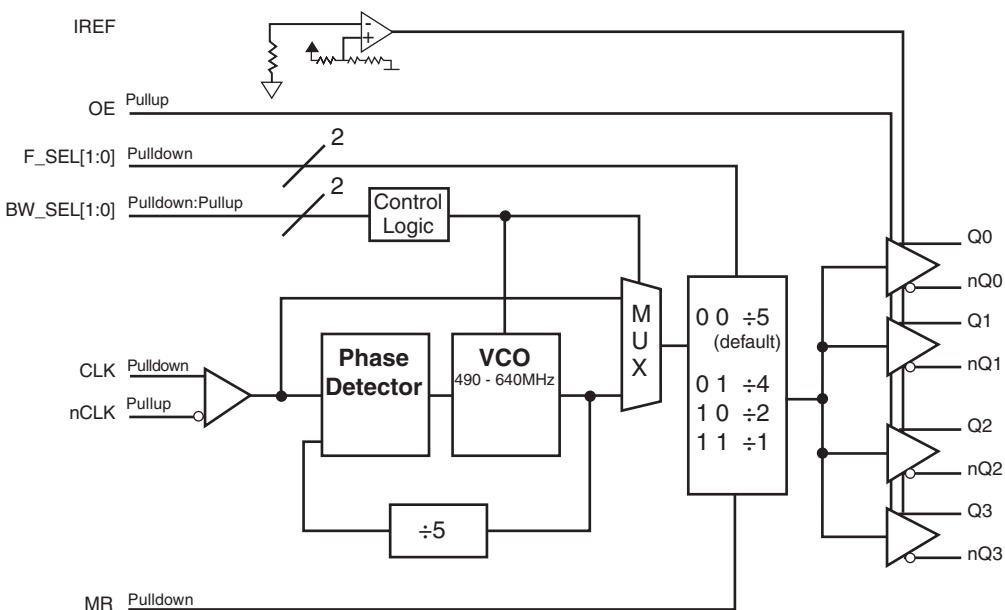
GENERAL DESCRIPTION



The ICS871004I-04 is a high performance Differential-to-0.7V Differential Jitter Attenuator designed for use in PCI Express™ systems. In some PCI Express systems, such as those found in desktop PCs, the PCI Express clocks are generated from a low bandwidth, highphase noise PLL frequency synthesizer. In these systems, a jitter attenuator may be required to attenuate high frequency random and deterministic jitter components from the PLL synthesizer and from the system board. The ICS871004I-04 has 3 PLL bandwidth modes: 200kHz, 400kHz and 800kHz. The 200kHz mode will provide maximum jitter attenuation, but with higher PLL tracking skew and spread spectrum modulation from the motherboard synthesizer may be attenuated. The 400kHz provides an intermediate bandwidth that can easily track triangular spread profiles, while providing good jitter attenuation. The 800kHz bandwidth provides the best tracking skew and will pass most spread profiles, but the jitter attenuation will not be as good as the lower bandwidth modes. The ICS871004I-04 can be set for different modes using the F_SEL pins as shown in Table 3C.

The ICS871004I-04 uses IDT's 3rd Generation FemtoClock™ PLL technology to achieve the lowest possible phase noise. The device is packaged in a 24 Lead TSSOP package, making it ideal for use in space constrained applications such as PCI Express add-in cards.

BLOCK DIAGRAM



Features

- Four 0.7V differential output pairs
- One differential clock input
- CLK and nCLK supports the following input types: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- Output frequency range: 98MHz - 640MHz
- Input frequency range: 98MHz - 128MHz
- VCO range: 490MHz - 640MHz
- Cycle-to-cycle jitter: 19ps (typical)
- Additive phase jitter, RMS: 0.23ps (typical)
- 3.3V operating supply
- Three bandwidth modes allow the system designer to make jitter attenuation/tracking skew design trade-offs
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

PLL BANDWIDTH

| | |
|-------------|------------------------------------|
| BW_SEL[1:0] | |
| 0 0 | = PLL Bandwidth: ~200kHz |
| 0 1 | = PLL Bandwidth: ~400kHz (default) |
| 1 0 | = PLL Bandwidth: ~800kHz |
| 1 1 | = PLL BYPASS |

PIN ASSIGNMENT

| | | | |
|------------------|----|----|-----------------|
| nQ0 | 1 | 24 | Q0 |
| nQ2 | 2 | 23 | V _{DD} |
| Q2 | 3 | 22 | Q1 |
| V _{DD} | 4 | 21 | nQ1 |
| IREF | 5 | 20 | Q3 |
| GND | 6 | 19 | nQ3 |
| MR | 7 | 18 | BW_SEL1 |
| BW_SEL0 | 8 | 17 | F_SEL1 |
| V _{DDA} | 9 | 16 | GND |
| F_SEL0 | 10 | 15 | GND |
| V _{DD} | 11 | 14 | nCLK |
| OE | 12 | 13 | CLK |

ICS871004I-04 24-Lead TSSOP

4.40mm x 7.8mm x 0.92mm
package body
G Package
Top View

The Preliminary Information presented herein represents a product in pre-production. The noted characteristics are based on initial product characterization and/or qualification. Integrated Device Technology, Incorporated (IDT) reserves the right to change any circuitry or specifications without notice.

TABLE 1. PIN DESCRIPTIONS

| Number | Name | Type | | Description |
|-----------|------------------|--------|----------|---|
| 1, 24 | nQ0, Q0 | Output | | Differential output pair. PCI Express interface levels. |
| 2, 3 | nQ2, Q2 | Output | | Differential output pair. PCI Express interface levels. |
| 4, 11, 23 | V _{DD} | Power | | Core supply pin. |
| 5 | IREF | Input | | A fixed precision resistor (475Ω) from this pin to ground provides a reference current used for differential current-mode QAx/nQAx and QBx/nQBx clock outputs. |
| 6, 15, 16 | GND | Power | | Power supply ground. |
| 7 | MR | Input | Pulldown | Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the true outputs (nQx) to go low and the inverted outputs (Qx) to go high. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS/LVTTL interface levels. |
| 8 | BW_SEL0 | Input | Pullup | Selects PLL Bandwidth input. LVCMOS/LVTTL interface levels. See Table 3B. |
| 9 | V _{DDA} | Power | | Analog supply pin. |
| 10, 17 | F_SEL0, F_SEL1 | Input | Pulldown | Frequency select pins. LVCMOS/LVTTL interface levels. See Table 3C. |
| 12 | OE | Input | Pullup | Output enable pin. When HIGH, the outputs are active. When LOW, the outputs are in a high impedance state. LVCMOS/LVTTL interface levels. |
| 13 | CLK | Input | Pulldown | Non-inverting differential clock input. |
| 14 | nCLK | Input | Pullup | Inverting differential clock input. |
| 18 | BW_SEL1 | Input | Pulldown | Selects PLL Bandwidth input. LVCMOS/LVTTL interface levels. See Table 3B. |
| 19, 20 | nQ3, Q3 | Output | | Differential output pair. PCI Express interface levels. |
| 21, 22 | nQ1, Q1 | Output | | Differential output pair. PCI Express interface levels. |

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------------|-------------------------|-----------------|---------|---------|---------|-------|
| C _{IN} | Input Capacitance | | | 4 | | pF |
| R _{PULLUP} | Input Pullup Resistor | | | 51 | | kΩ |
| R _{PULLDOWN} | Input Pulldown Resistor | | | 51 | | kΩ |

TABLE 3A. OUTPUT ENABLE FUNCTION TABLE

| Inputs | Outputs | |
|--------|---------|---------|
| | Q0:Q3 | nQ0:nQ3 |
| 0 | HiZ | HiZ |
| 1 | Enabled | Enabled |

TABLE 3B. PLL BANDWIDTH/PLL BYPASS CONTROL

| Inputs | | PLL Bandwidth |
|---------|---------|-------------------|
| BW_SEL1 | BW_SEL0 | |
| 0 | 0 | ~200kHz |
| 0 | 1 | ~400kHz (default) |
| 1 | 0 | ~800kHz |
| 1 | 1 | PLL BYPASS |

TABLE 3C. FREQUENCY SELECT FUNCTION TABLE

| Input Frequency | Inputs | | | Output Frequency Range (MHz) |
|-----------------|--------|--------|---------------|------------------------------|
| | F_SEL1 | F_SEL0 | Divider Value | |
| 100 | 0 | 0 | 5 | 100 (default) |
| 100 | 0 | 1 | 4 | 125 |
| 100 | 1 | 0 | 2 | 250 |
| 100 | 1 | 1 | 1 | 500 |

ABSOLUTE MAXIMUM RATINGS

| | |
|--|--------------------------|
| Supply Voltage, V_{DD} | 4.6V |
| Inputs, V_I | -0.5V to $V_{DD} + 0.5V$ |
| Outputs, V_O | -0.5V to $V_{DD} + 0.5V$ |
| Package Thermal Impedance, θ_{JA} | 82.3°C/W (0 mps) |
| Storage Temperature, T_{STG} | -65°C to 150°C |

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = V_{DDA} = 3.3V \pm 10\%$, $T_A = -40^\circ\text{C}$ TO 85°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|-----------------------|-----------------|-------------------------------|---------|----------|-------|
| V_{DD} | Core Supply Voltage | | 3.135 | 3.3 | 3.465 | V |
| V_{DDA} | Analog Supply Voltage | | $V_{DD} - I_{DDA} * 10\Omega$ | 3.3 | V_{DD} | V |
| I_{DD} | Power Supply Current | | | TBD | | mA |
| I_{DDA} | Analog Supply Current | | | TBD | | mA |

TABLE 4B. LVCMOS/LVTTL DC CHARACTERISTICS, $V_{DD} = V_{DDA} = 3.3V \pm 10\%$, $T_A = -40^\circ\text{C}$ TO 85°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|--------------------|-----------------------------|--------------------------------|---------|----------------|---------------|
| V_{IH} | Input High Voltage | MR, OE, F_SEL0, F_SEL1, | 2 | | $V_{DD} + 0.3$ | V |
| | | BW_SEL0, BW_SEL1 | $V_{DD} - 0.3$ | | $V_{DD} + 0.3$ | V |
| V_{IL} | Input Low Voltage | MR, OE, F_SEL0, F_SEL1, | -0.3 | | 0.8 | V |
| | | BW_SEL0, BW_SEL1 | -0.3 | | 0.3 | V |
| I_{IH} | Input High Current | BW_SEL0, OE | $V_{DD} = V_{IN} = 3.465V$ | | 5 | μA |
| | | MR, BW_SEL1, F_SEL0, F_SEL1 | $V_{DD} = V_{IN} = 3.465V$ | | 150 | μA |
| I_{IL} | Input Low Current | BW_SEL0, OE | $V_{DD} = 3.465V, V_{IN} = 0V$ | | -150 | μA |
| | | MR, BW_SEL1, F_SEL0, F_SEL1 | $V_{DD} = 3.465V, V_{IN} = 0V$ | | -5 | μA |

TABLE 4C. DIFFERENTIAL DC CHARACTERISTICS, $V_{DD} = V_{DDA} = 3.3V \pm 10\%$, $T_A = -40^\circ\text{C}$ TO 85°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------|--------------------------------------|-----------------|----------------------------|---------|-----------------|---------------|
| I_{IH} | Input High Current | CLK | $V_{DD} = V_{IN} = 3.465V$ | | 150 | μA |
| | | nCLK, | $V_{DD} = V_{IN} = 3.465V$ | 5 | | μA |
| I_{IL} | Input Low Current | CLK | $V_{DD} = V_{IN} = 3.465V$ | | 150 | μA |
| | | nCLK | $V_{DD} = V_{IN} = 3.465V$ | -150 | | μA |
| V_{PP} | Peak-to-Peak Input Voltage | | 0.15 | | 1.3 | V |
| V_{CMR} | Common Mode Input Voltage; NOTE 1, 2 | | GND + 0.5 | | $V_{DD} - 0.85$ | V |

NOTE 1: Common mode voltage is defined as V_{IH} .

NOTE 2: For single ended applications, the maximum input voltage for CLK, nCLK at $V_{DD} + 0.3V$.

TABLE 5. AC CHARACTERISTICS, $V_{DD} = V_{DDA} = 3.3V \pm 10\%$, $T_A = -40^\circ\text{C}$ TO 85°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|---------------------------|--|---|---------|---------|------------------|-------|
| f_{MAX} | Output Frequency | | 98 | | 640 | MHz |
| t_{PD} | Propagation Delay; NOTE 1 | PLL in BYPASS Mode | | 3.8 | | ns |
| f_{jit} | Buffer Additive Phase Jitter, RMS; Refer to Additive Phase Jitter Section | PLL in BYPASS Mode 100MHz, Integration Range: 12kHz - 20MHz | | 0.23 | | ps |
| $f_{jit}(cc)$ | Cycle-to-Cycle Jitter; NOTE 2 | PLL Mode | | 19 | | ps |
| t_L | PLL Lock Time | | | TBD | | ms |
| V_{HIGH} | Voltage High | | 660 | | 850 | mV |
| V_{LOW} | Voltage Low | | -150 | | | mV |
| V_{OVS} | Max. Voltage, Overshoot | | | | $V_{HIGH} + 0.3$ | V |
| V_{UDS} | Min. Voltage, Undershoot | | -0.3 | | | V |
| V_{rb} | Ringback Voltage | | | | 0.2 | V |
| V_{CROSS} | Absolute Crossing Voltage | | 250 | | 550 | mV |
| ΔV_{CROSS} | Total Variation of V_{CROSS} over all edges | | | | 140 | mV |
| t_R / t_F | Output Rise/Fall Time | measured between 0.175 to 0.525 | | 475 | | ps |
| $\Delta t_R / \Delta t_F$ | Rise/Fall Time Variation | | | | 125 | ps |
| t_{RFM} | Rise/Fall Matching | | | | 125 | ps |
| odc | Output Duty Cycle | | | 50 | | % |

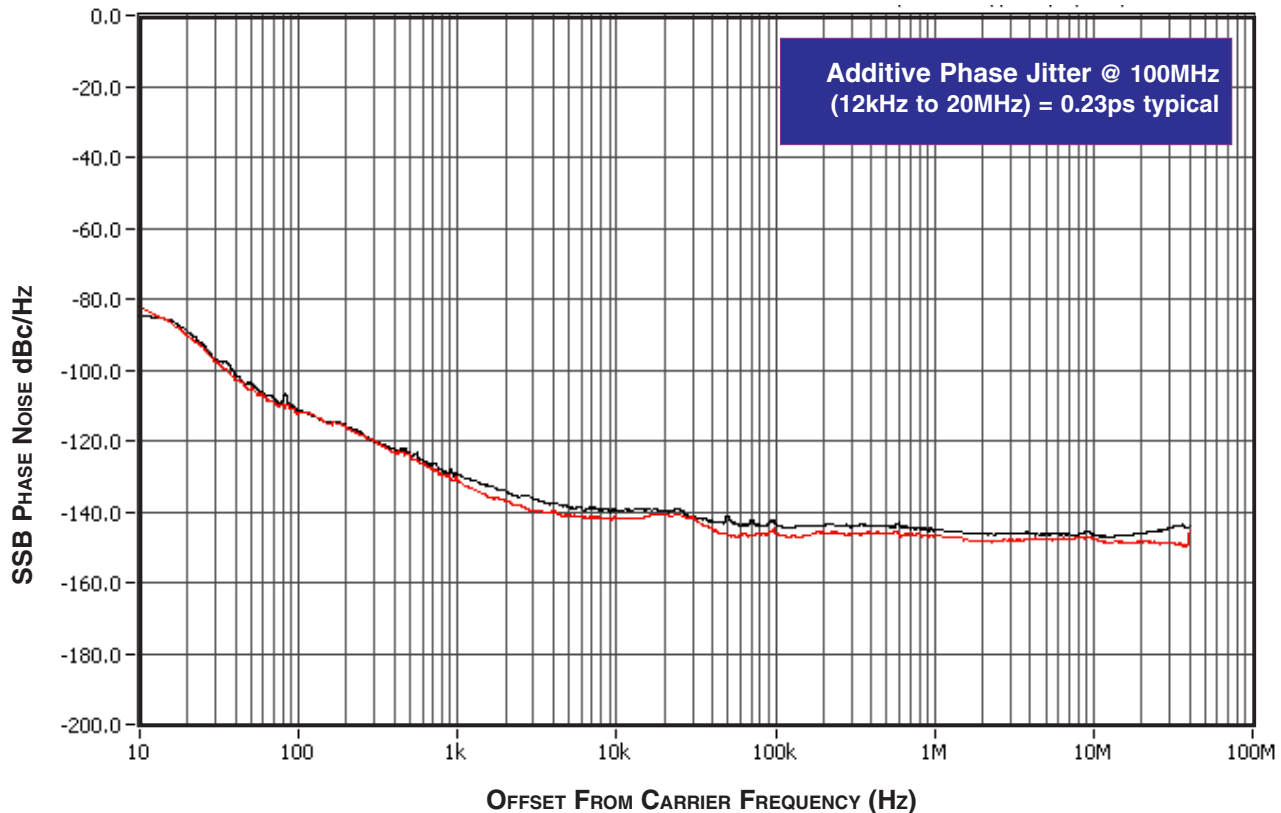
NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise***. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the 1Hz

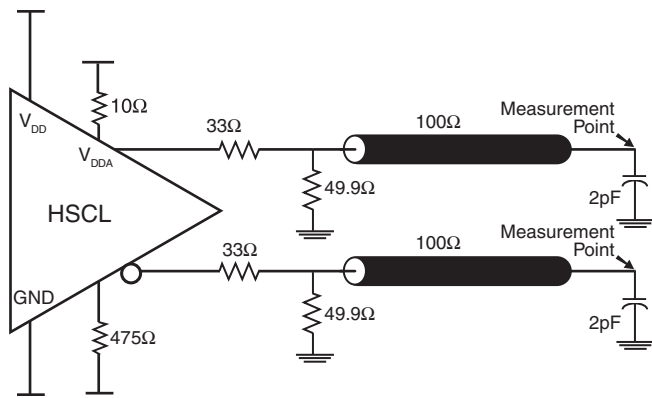
band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



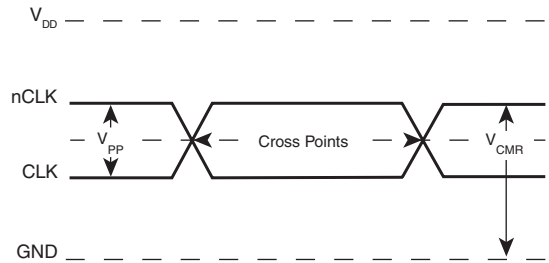
As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device

meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.

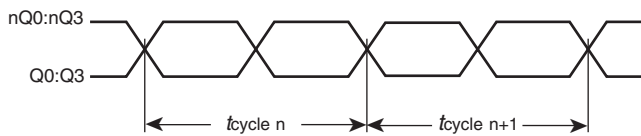
PARAMETER MEASUREMENT INFORMATION



3.3V HCSL OUTPUT LOAD AC TEST CIRCUIT - TBD



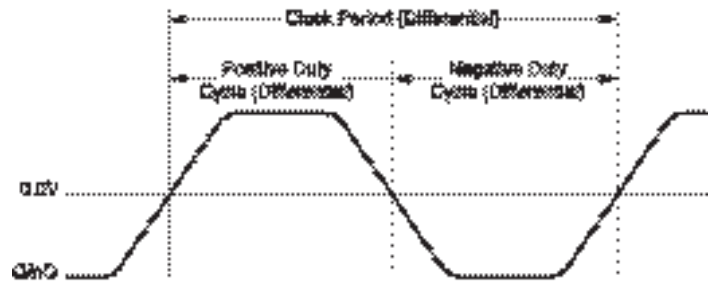
DIFFERENTIAL INPUT LEVEL



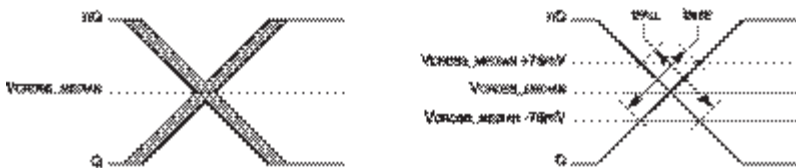
$$t_{jit(cc)} = t_{cycle\ n} - t_{cycle\ n+1}$$

1000 Cycles

CYCLE-TO-CYCLE JITTER

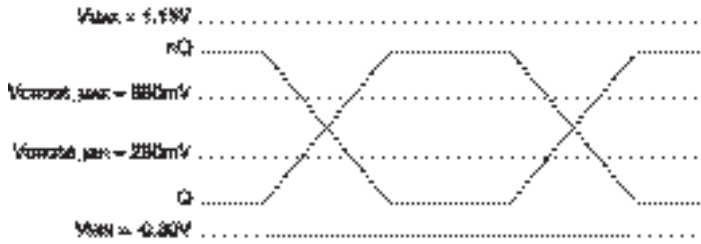


DIFFERENTIAL MEASUREMENT POINTS FOR DUTY CYCLE/PERIOD

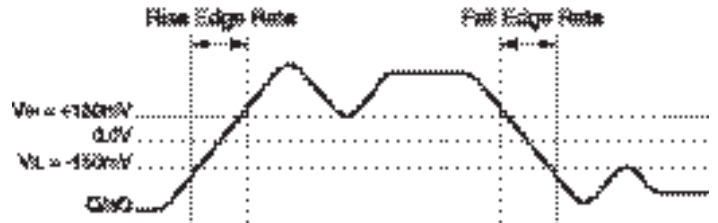


SE MEASUREMENT POINTS FOR RISE/FALL TIME MATCHING

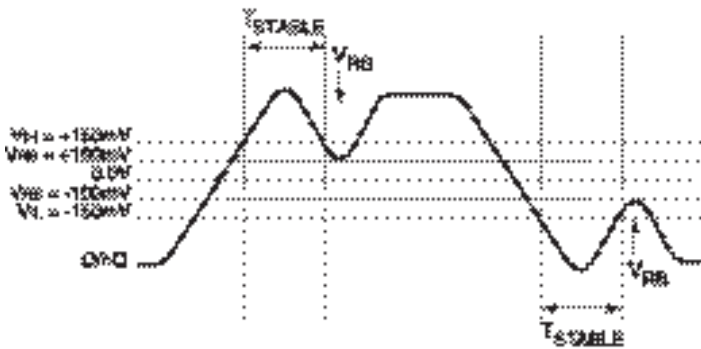
PARAMETER MEASUREMENT INFORMATION, CONTINUED



SE MEASUREMENT POINTS FOR ABSOLUTE CROSS POINT/SWING



DIFFERENTIAL MEASUREMENT POINTS FOR RISE/FALL TIME



DIFFERENTIAL MEASUREMENT POINTS FOR RINGBACK



SE MEASUREMENT POINTS FOR DELTA CROSS POINT

APPLICATION INFORMATION

POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The ICS871004I-04 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{DD} , V_{DDA} and V_{DDO} should be individually connected to the power supply plane through vias, and $0.01\mu\text{F}$ bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic V_{DD} pin and also shows that V_{DDA} requires that an additional 10Ω resistor along with a $10\mu\text{F}$ bypass capacitor be connected to the V_{DDA} pin.

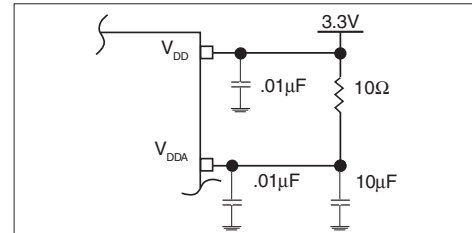


FIGURE 1. POWER SUPPLY FILTERING

RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS:

LVC MOS CONTROL PINS

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A $1\text{k}\Omega$ resistor can be used.

OUTPUTS:

DIFFERENTIAL OUTPUTS

All unused differential outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{DD}/2$ is generated by the bias resistors $R1$, $R2$ and $C1$. This bias circuit should be located as close as possible to the input pin. The ratio

of $R1$ and $R2$ might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{DD} = 3.3\text{V}$, V_{REF} should be 1.25V and $R2/R1 = 0.609$.

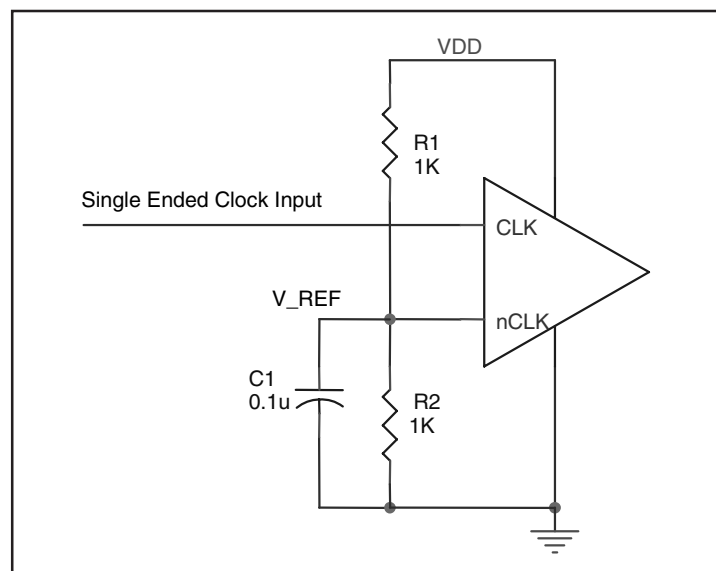


FIGURE 2. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT

DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 3A to 3F show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver

component to confirm the driver termination requirements. For example in Figure 3A, the input termination applies for IDT HiPerClockS open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

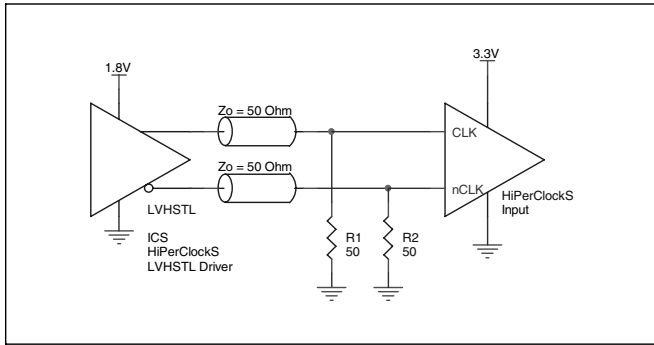


FIGURE 3A. HiPerClockS CLK/nCLK INPUT DRIVEN BY AN IDT OPEN EMITTER HiPerClockS LVHSTL DRIVER

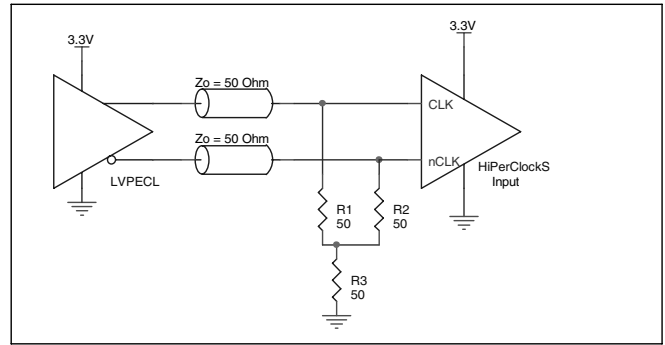


FIGURE 3B. HiPerClockS CLK/nCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER

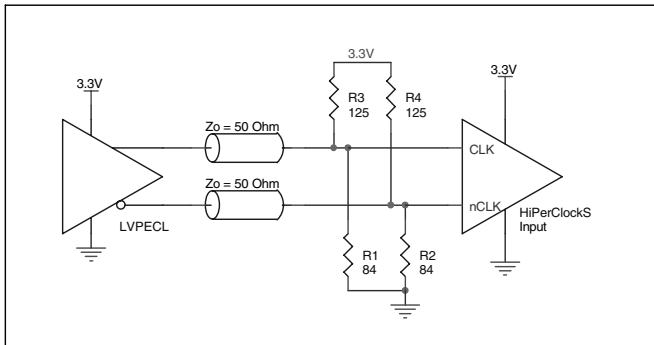


FIGURE 3C. HiPerClockS CLK/nCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER

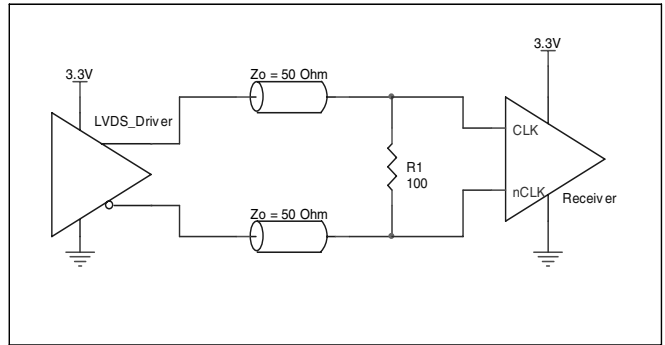


FIGURE 3D. HiPerClockS CLK/nCLK INPUT DRIVEN BY A 3.3V LVDS DRIVER

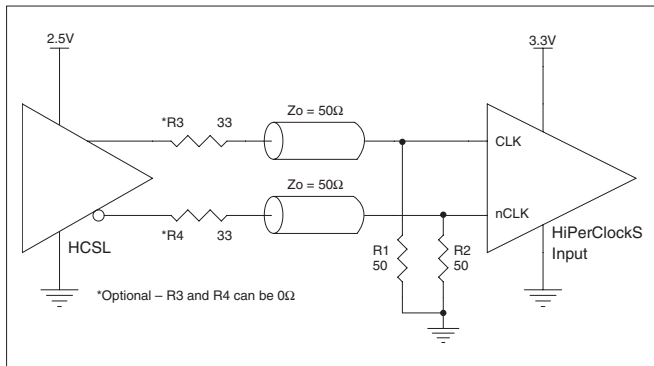


FIGURE 3E. HiPerClockS CLK/nCLK INPUT DRIVEN BY A 3.3V HCSL DRIVER

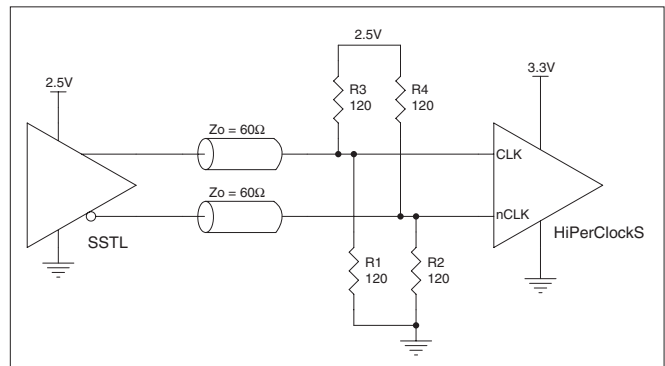


FIGURE 3F. HiPerClockS CLK/nCLK INPUT DRIVEN BY A 2.5V SSTL DRIVER

RECOMMENDED TERMINATION

Figure 4A is the recommended termination for applications which require the receiver and driver to be on a separate PCB. All traces should be 50Ω impedance.

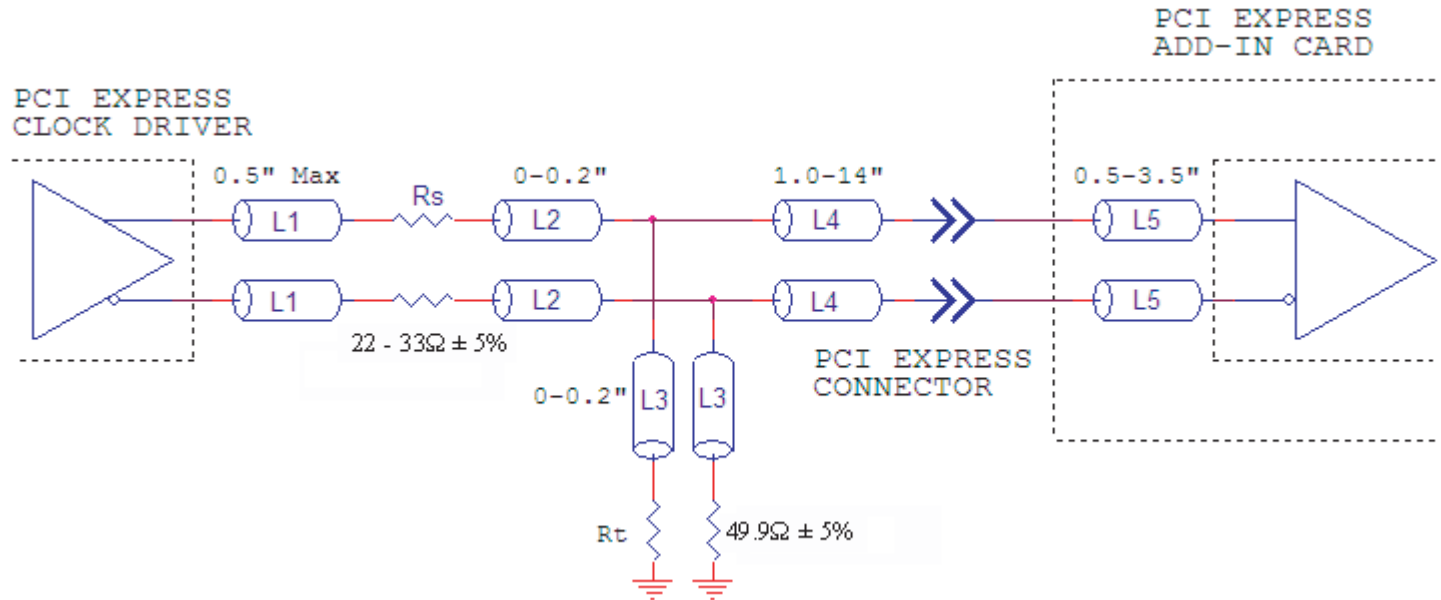


FIGURE 4A. RECOMMENDED TERMINATION

Figure 6B is the recommended termination for applications which require a point to point connection and contain the driver

and receiver on the same PCB. All traces should all be 50Ω impedance.

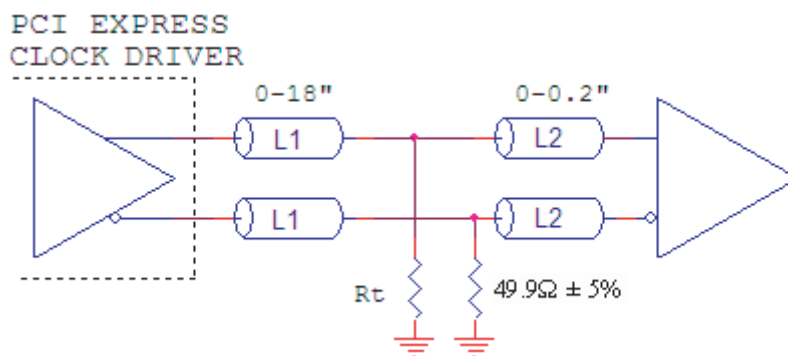


FIGURE 4B. RECOMMENDED TERMINATION

RELIABILITY INFORMATION

TABLE 6. θ_{JA} vs. AIR FLOW TABLE FOR 24 LEAD TSSOP

| θ_{JA} by Velocity (Meters per Second) | | | |
|---|----------|--------|----------|
| | 0 | 1 | 2.5 |
| Multi-Layer PCB, JEDEC Standard Test Boards | 82.3°C/W | 78°C/W | 75.9°C/W |

TRANSISTOR COUNT

The transistor count for ICS871004I-04 is: 1395

PACKAGE OUTLINE - G SUFFIX FOR 24 LEAD TSSOP

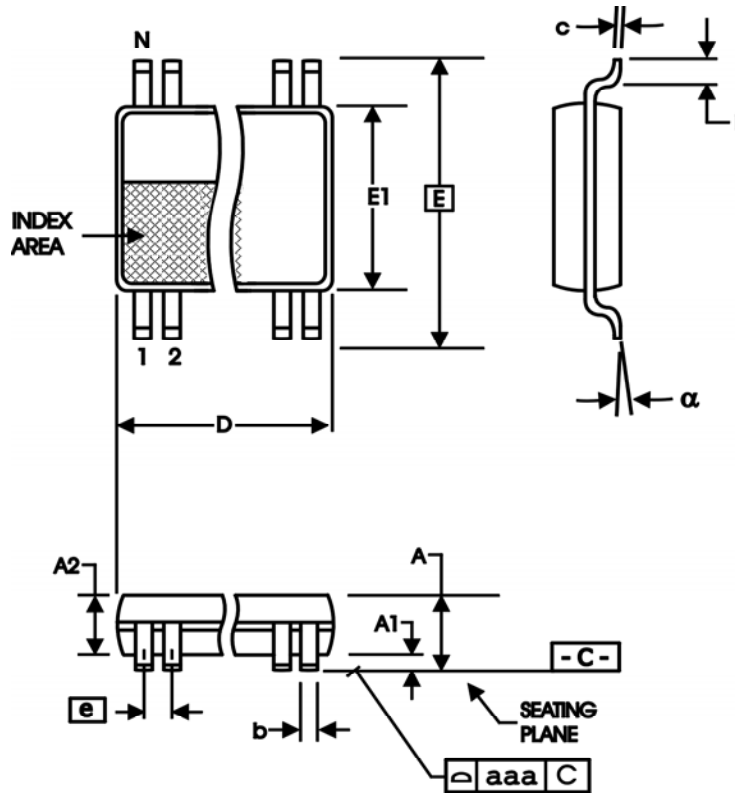


TABLE 7. PACKAGE DIMENSIONS

| SYMBOL | Millimeters | |
|----------|-------------|---------|
| | Minimum | Maximum |
| N | 24 | |
| A | -- | 1.20 |
| A1 | 0.05 | 0.15 |
| A2 | 0.80 | 1.05 |
| b | 0.19 | 0.30 |
| c | 0.09 | 0.20 |
| D | 7.70 | 7.90 |
| E | 6.40 BASIC | |
| E1 | 4.30 | 4.50 |
| e | 0.65 BASIC | |
| L | 0.45 | 0.75 |
| α | 0° | 8° |
| aaa | -- | 0.10 |

Reference Document: JEDEC Publication 95, MO-153

TABLE 8. ORDERING INFORMATION

| Part/Order Number | Marking | Package | Shipping Packaging | Temperature |
|--------------------|---------------|---------------------------|--------------------|---------------|
| ICS871004AGI-04 | ICS871004AI04 | 24 Lead TSSOP | tube | -40°C to 85°C |
| ICS871004AGI-04T | ICS871004AI04 | 24 Lead TSSOP | 2500 tape & reel | -40°C to 85°C |
| ICS871004AGI-04LF | ICS71004AI04L | 24 Lead "Lead-Free" TSSOP | Tray | -40°C to 85°C |
| ICS871004AGI-04LFT | ICS71004AI04L | 24 Lead "Lead-Free" TSSOP | 2500 Tape & Reel | -40°C to 85°C |

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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